

STC08IE150HV

Emitter switched bipolar transistor $\mathsf{ESBT}^{\mathbb{R}}$ 1500V - 8A - 0.08 Ω

Features

V _{CS(ON)}	۱ _C	R _{CS(ON)}
0.65 V	8 A	0.08 Ω

- High voltage / high current cascode configuration
- Low equivalent on resistance
- Very fast-switch, up to 150 kHz
- Squared RBSOA, up to 1500 V
- Very low C_{ISS} driven by $R_G = 4.7 \Omega$
- Very low turn-off cross over time

Application

- Aux SMPS for three phase mains
- PFC

Description

The STC08IE150HV is manufactured in monolithic ESBT technology, aimed to provide best performance in high frequency / high voltage applications. it is designed for use in gate driven based topologies.

	Table 1. Device summary						
Part number		Marking	Package	Packaging			
STC08IE150HV		C08IE150HV	TO247-4L HV	Tube			

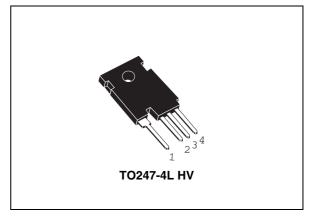
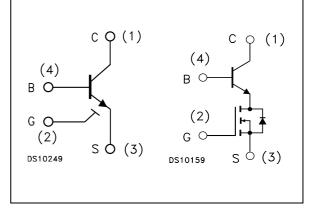


Figure 1. Internal schematic diagrams



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1 Electrical ratings

Table 2.	Absolute maximum ratings
	Absolute maximum rutings

Symbol	Parameter	Value	Unit	
V _{CS(SS)}	Collector-source voltage ($V_{BS} = V_{GS} = 0$)	1500	V	
V _{BS(OS)}	Base-source voltage (I _C =0, V _{GS} =0)	30	V	
V _{SB(OS)}	Source-base voltage (I _C =0, V _{GS} =0)	17	V	
V_{GS}	Gate-source voltage	± 17	V	
۱ _C	Collector current	8	А	
I _{CM}	Collector peak current (t _P < 1 ms)	24	А	
Ι _Β	Base current	8	А	
I _{BM}	Base peak current (t _P < 1 ms)	12	А	
P _{tot}	Total dissipation at $T_c \le 25^{\circ}C$	208	W	
T _{stg}	Storage temperature	-40 to 150	°C	
Τ _J	Max. operating junction temperature	125	°C	

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.6	°C/W

2 Electrical characteristics

 $(T_{case} = 25^{\circ}C \text{ unless otherwise specified})$

Table 4.	Electrical characteristics					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{CS(SS)}	Collector-source cut-off current ($V_{BS} = V_{GS} = 0$)	V _{CS} =1500 V			100	μA
I _{BS(OS)}	Base-source cut-off current (I _C =0, V _{GS} =0)	V _{BS} =30 V			10	μA
I _{SB(OS)}	Source-base cut-off current ($I_C = 0$, $V_{GS} = 0$)	V _{SB} =17 V			100	μA
I _{GS(OS)}	Gate-source cut-off current (I _C =0; V _{BS} =0)	V _{GS} = ± 17 V			100	nA
V _{CS(ON)}	Collector-source on voltage	$V_{GS} = 10 V I_C = 3 A I_B = 0.3 A$ $V_{GS} = 10 V I_C = 8 A I_B = 1.6 A$		0.3 0.65	1.2 1.5	V V
h _{FE}	DC current gain		9 4.5	14 6.8		
V _{BS(ON)}	Base-source on voltage	$V_{GS} = 10 V I_C = 3 A I_B = 0.3 A$ $V_{GS} = 10 V I_C = 8 A I_B = 1.6 A$		1 1.7	1.5 2	V V
V _{GS(th)}	Gate threshold voltage	$V_{BS} = V_{GS}$ $I_B = 250 \ \mu A$	2	3	4	V
C _{iss}	Input capacitance	$V_{CS} = 25 V$ f = 1 MHz $V_{GS} = V_{CB} = 0$		810		pF
Q _{GS(tot)}	Gate-source charge	$\begin{array}{ccc} V_{CS}\!\!=\!\!25V & V_{GS}\!\!=\!\!10V \\ V_{CB}\!\!=\!\!0 & I_{C}\!=\!\!4A \end{array}$		45		nC
t _s t _f	Inductive load Storage time Fall time	$\label{eq:VGS} \begin{array}{ll} V_{GS} = \! 10 \ V & R_G = \! 4.7 \ \Omega \\ V_{clamp} = \! 1200 V & t_p = \! 4 \ \mu s \\ I_C = \! 4 \ A & I_B = \! 0.8 \ A \end{array}$		690 10		ns ns
t _s t _f	Inductive load Storage time Fall time	$\label{eq:VGS} \begin{array}{ll} V_{GS} = 10 \ V & R_G = 4.7 \ \Omega \\ V_{clamp} = 1200 \ V & t_p = 4 \ \mu s \\ I_C = 4 \ A & I_B = 0.4 \ A \end{array}$		340 10		ns ns
V _{CS(dyn)}	Collector-source dynamic voltage (500 ns)	$\label{eq:V_CC} \begin{split} & V_{CC} = V_{clamp} = 600 \ V \\ & V_{GS} = 10 \ V \\ & I_{B} = 0.4 \ A \\ & t_{(peak)} = 500 \ ns \\ \end{split} \\ \begin{aligned} & I_{B}(peak) = 4 \ A \end{split}$		2.8		V

 Table 4.
 Electrical characteristics

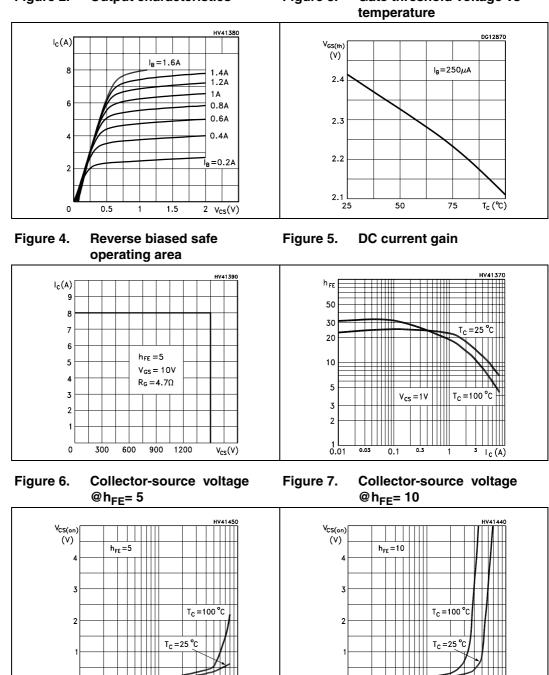


		· /				
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{CS(dyn)}	Collector-source dynamic voltage (1 μs)	$\begin{array}{ll} V_{CC} = \!$		1.7		v
V _{CSW}	Maximum collector- source voltage switched without snubber	$R_{G} = 4.7 \Omega$ $h_{FE} = 5$ $I_{C} = 8 A$	1500			V

 Table 4.
 Electrical characteristics (continued)



Electrical characteristics (curves) 2.1



0 0.1

0.2

0.4 0.6

1

Figure 2. **Output characteristics**

Figure 3. Gate threshold voltage vs

 $I_{c}(A)$

0

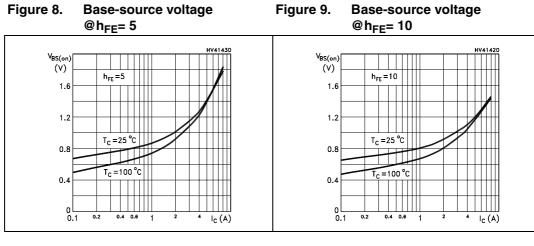
0.2

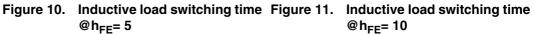
0.4 0.6

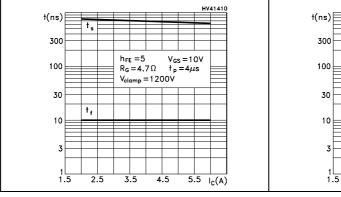
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 $I_{c}(A)$

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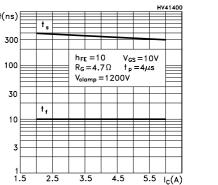
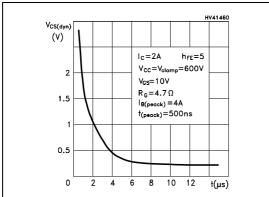


Figure 12. Dynamic collector-source voltage



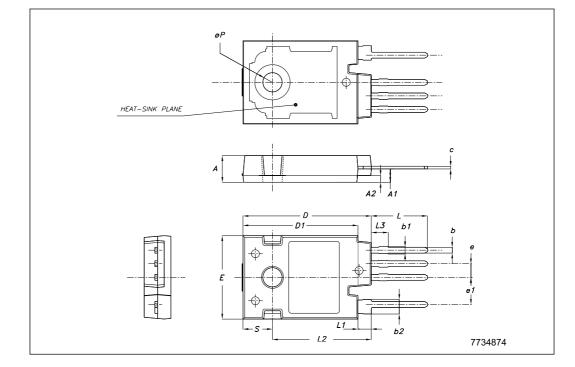
3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



ом.		mm.	
	MIN.	ТҮР	MAX.
A	4.85		5.15
A1	2.20	2.50	2.60
A2		1.27	
b	0.95	1.10	1.30
b2	2.50		2.90
с	0.40		0.80
D	23.85	24	24.15
D1		21.50	
E	15.45	15.60	15.75
е	2.54		
e1	5.08		
L	10.20		10.80
L1	2.20	2.50	2.80
L2		18.50	
L3		3	
ØP	3.55		3.65
S		5.50	

TO247-4L HV MECHANICAL DATA



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4 Revision history

Table 5.Document revision history

Date	Revision	Changes	
30-Jan-2006	1	First release	
01-Dec-2006	ec-2006 2 The document has been reformatted, no content change		
22-Nov-2007	3	Document status promoted from preliminary data to datasheet. Added Section 2.1: Electrical characteristics (curves)	



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